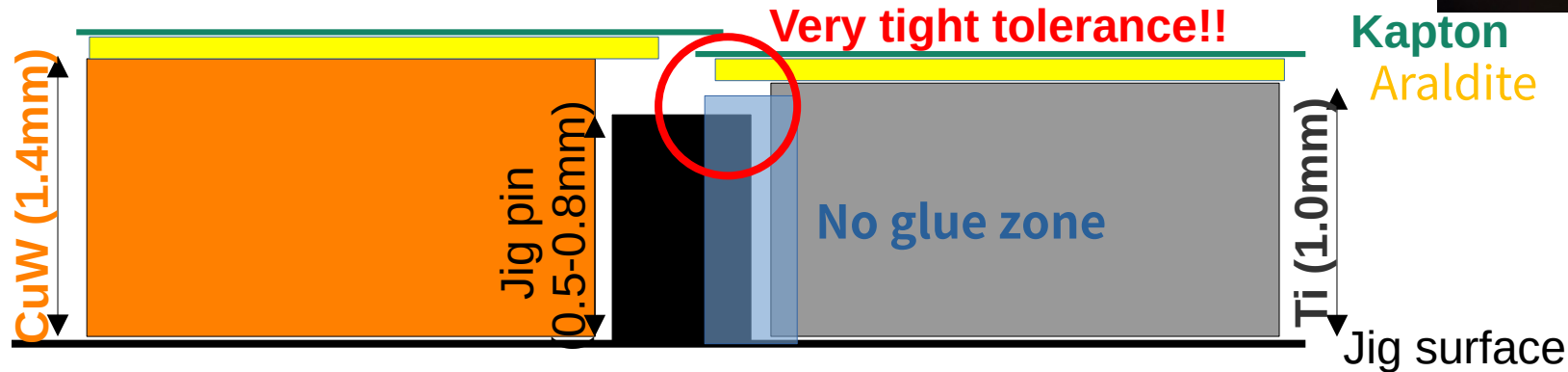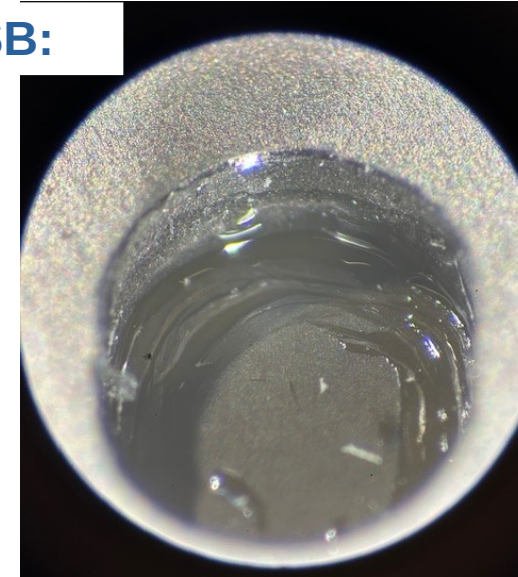# Alignment hole/slot cleaning

Both **IHEP** and **UCSB** has made statements about excess glue being present in the alignment holese:

- **IHEP** should be loose transfer tape (recoverable)
- **UCSB** sees **epoxy** (*potentially unrecoverable!*)

Clarification with NTU on cleaniness requirement

- Insert of 0.8-1.0 (!!)mm depth section should be free of glue. Effectively must be **completely glue free** for Ti plates

UCSB:

Very tight tolerance!!

Kapton
Araldite

CuW (1.4mm)

Jig pin (0.5-0.8mm)

No glue zone

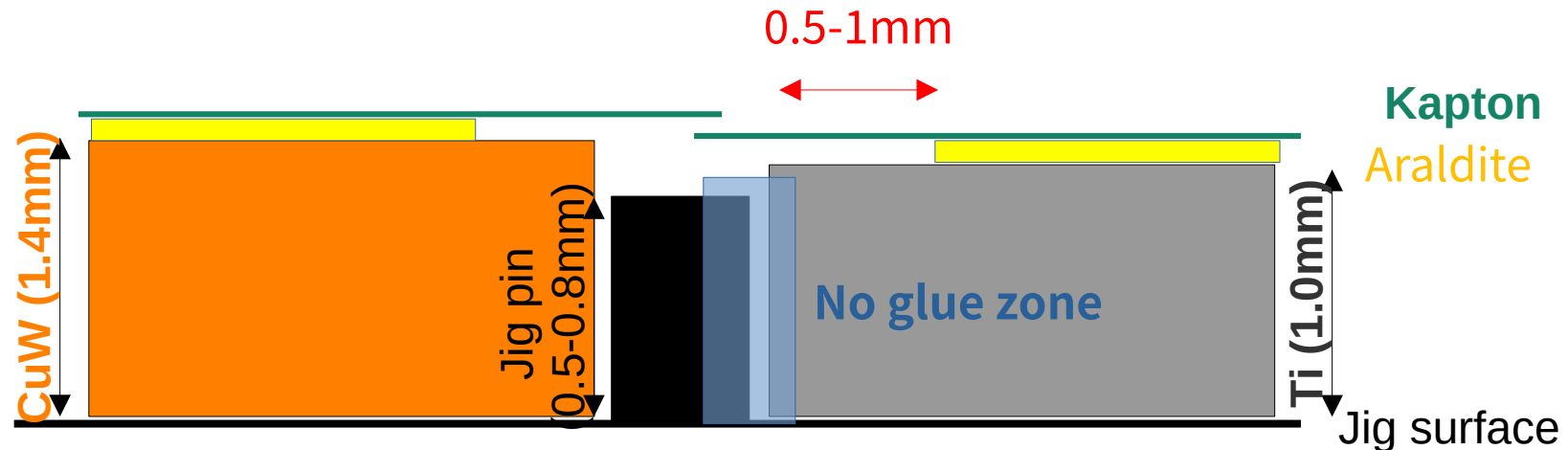Ti (1.0mm)

Jig surface

1

Alignment hole/slot cleaning

Proposed alteration to procedure (UCSB agrees with this)

Use "something" to clear ~1mm of glue from the alignment slots after *dispensing glue.*

- What is "something"?
Small piece of clean wipes (for next batch)?
Custom tool (to eliminate operator variance)?

Backplane notch/edge cleaning

Edges notches houses the PCB power plane-Si wire bonding area. As long as no glue overflows beyond the kapton we should be fine

Proposed alteration to procedure:

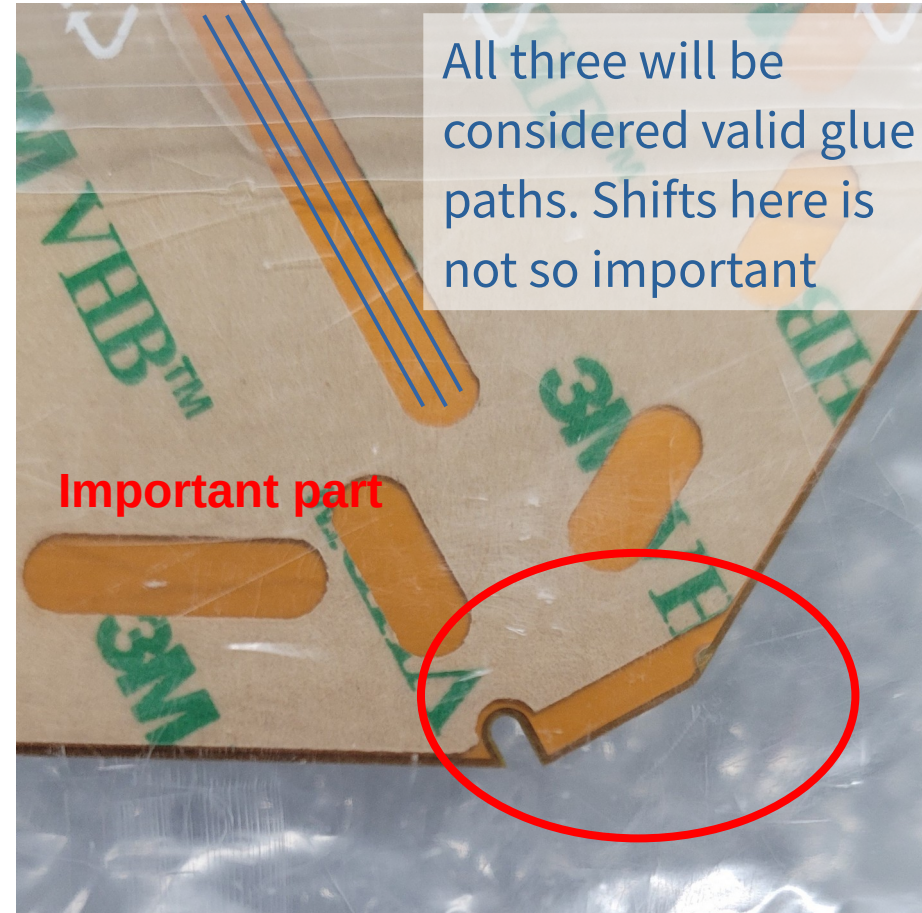We don't clean the notches so thoroughly, just make sure no glue exceeds Kapton.

PCB power plane pad

Silicon sensor

Protective resin (applied after wire bonding)

Al bonding wires
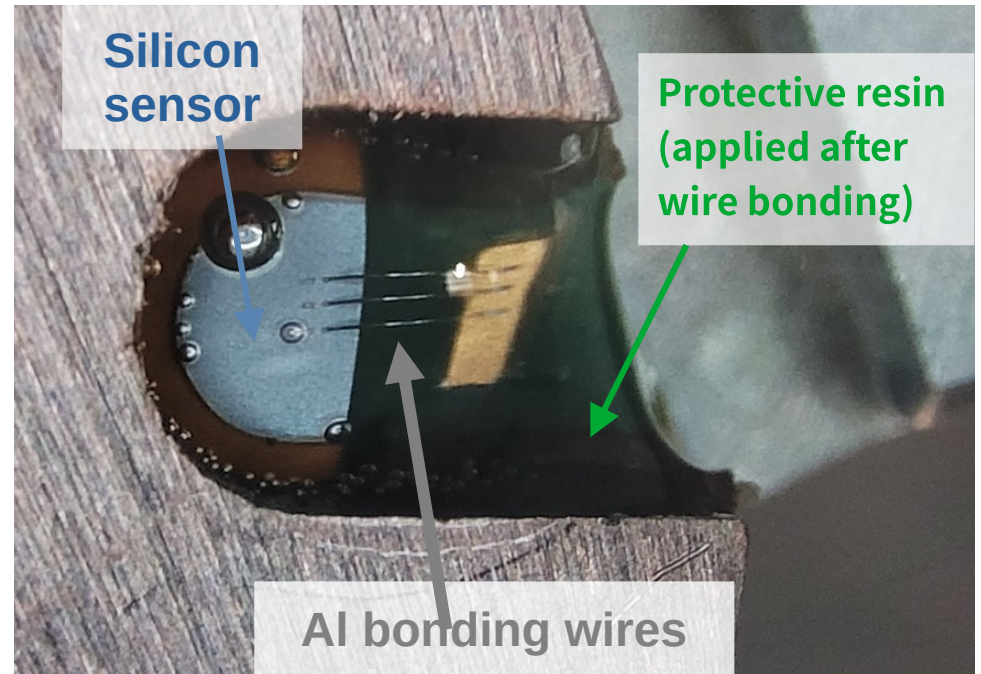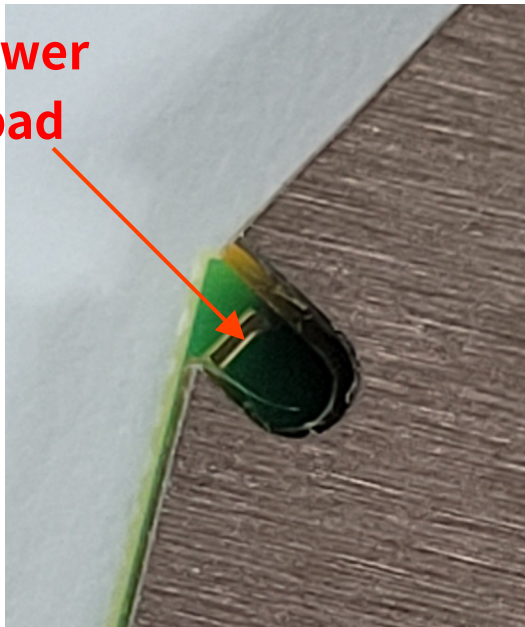
Transfer tape - alignment

MAC assembly uses single-line glue dispensing for the slits. As long as the notches and the grounding pad is properly exposed, alignment does not need to be strict.

No adjustment needed!

All three will be considered valid glue paths. Shifts here is not so important

Important part

Transfer tape - measurement

NTU has asked whether we will provided flatness measure of the assembly with transfer tape. This is a bit odd, since:

- Transfer tape is *not flat* by constructions
- Excluding transfer tape holes, we can only measure assembly with transfer tape + protective cover paper. They will still need to assert that tat the protective paper is flat as an assumption.
- *Should we adjust when flatness measure is performed?*

Shipping requests

- Nothing to complain for packaging quality (KIT is currently providing the best packaging, and that is including the critical and delicate silicon sensors…)
- They request that "tax forms always be filled out". Even if the final shipment is not taxed, not doing this will require NTU people to receive the package with an extra deposit (extra paper work)
  - December shipment had this problem, Summer shipment did not.
    Has our procedure changed?
  - Would this be automatically solved with everything going through CERN?
- The request for shipping the boxes back has been lost in transit somewhere…
  - It might be better if we contact the MAC operators?